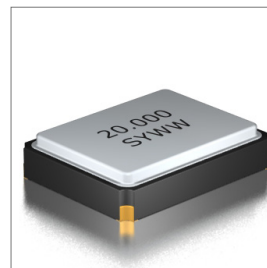


Features

- $\pm 10\text{ppm}/\pm 10\text{ppm}$ (Tolerance/Stability) Available
- Ultra-Miniature Package
- AT-Cut Fundamental
- Tape and Reel

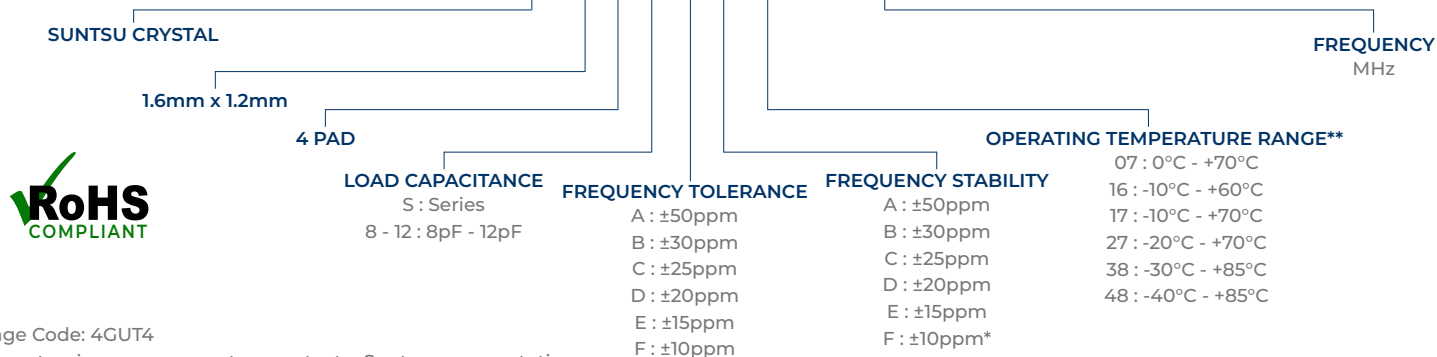
Applications

- Bluetooth
- Wireless LAN
- High Density Applications



Part Numbering Guide

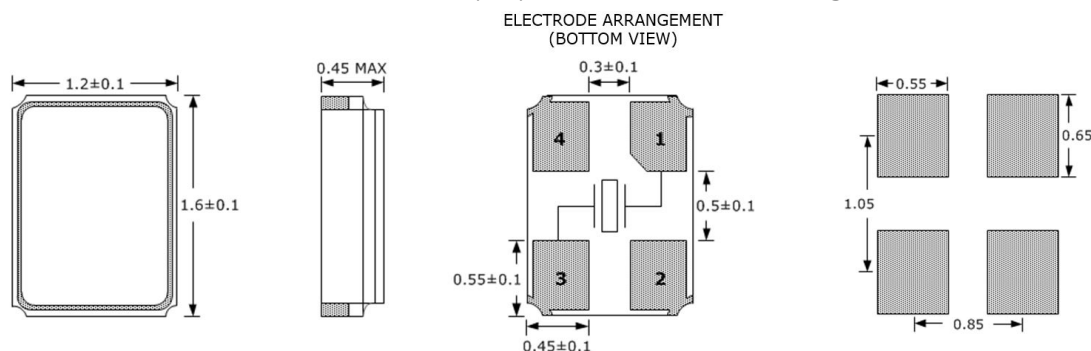
SXT 11 4 12 A A 48 - 20.000M



Electrical Parameters	Units	Minimum	Typical	Maximum	Remarks
Frequency Range	MHz	24		54	AT-Cut Fundamental.
Frequency Tolerance at +25°C	ppm	-10		+10	See part numbering guide for options.
Frequency Stability vs. Op Temp	ppm	-10		+10	See part numbering guide for options.
Frequency Stability vs. Aging	ppm	-2		+2	First year @ +25°C.
Operating Temperature	°C	-40		+85	See part numbering guide for options.
Storage Temperature	°C	-40		+95	
Load Capacitance	pF	8		12	See part numbering guide for options.
Shunt Capacitance	pF			3	
Drive Level	μW		10	100	
Insulation Resistance	MΩ	500			@ 100VDC ± 15V.
ESR - 24.000MHz ~ 29.999MHz	Ω			150	AT-Cut Fundamental
ESR - 30.000MHz ~ 54.000MHz	Ω			100	AT-Cut Fundamental

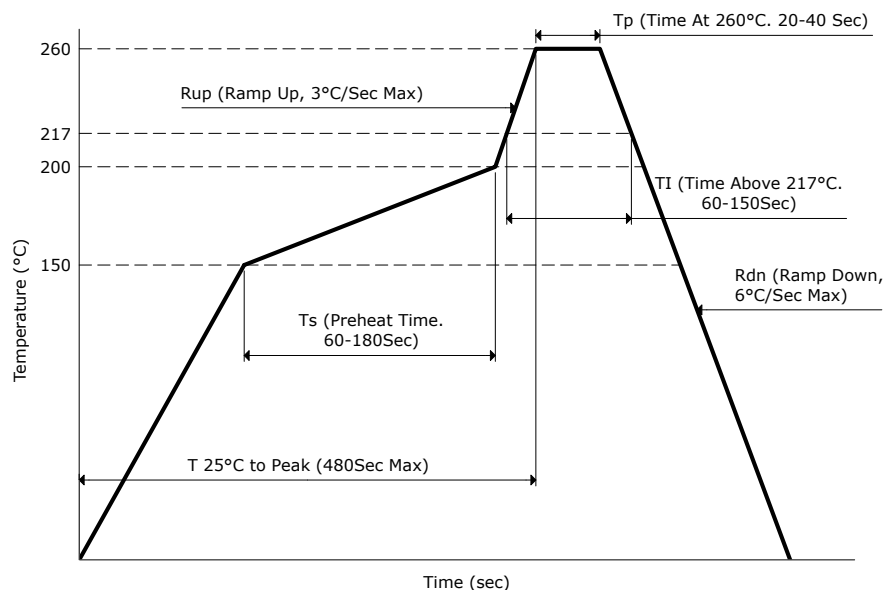
Outline Drawing & Recommended Landed Pattern

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.



Environmental Specifications		Mechanical Specifications	
Temperature Cycling	MIL-STD-883, Method 1010, Condition B	Mechanical Shock	MIL-STD-202, Method 213, Condition B
Fine Leak Test	MIL-STD-883, Method 1014, Condition A	Vibration	MIL-STD-883, Method 2007, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C	Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Moisture Resistance	MIL-STD-883, Method 1004	Resistance to Solvents	MIL-STD-202, Method 215
Moisture Sensitivity	J-STD-020, MSL 1	Solderability	MIL-STD-883, Method 2003

Reflow Profile & Part Marking



Frequency in MHz

Line 1: X X.X X

Line 2: S Y WW

Suntsu

Week

Year

Tape And Reel Dimensions

All dimensions are in millimeters (mm) unless otherwise noted. Drawings are not to scale.

3,000pcs / Reel

